

09/18 U.S. PTO  
09/817694  
03/26/01

Specializing in Patents,  
Trademarks, Copyrights and  
other Intellectual Property  
Matters

## Navarro IP Law Group, P.C.

A Professional Corporation  
801 E. Campbell Road  
Suite 655  
Richardson, Texas 75081

(972) 238-7160 - Tel  
(972) 238-7013 - Fax  
gary.honeycutt@iplaw-group.com

March 23, 2001

EL690653937US

### VIA EXPRESS MAIL

Assistant Commissioner for Patents  
Washington, D.C. 20231

Re: Patent Application For  
**Fixture and Method for Uniform Electroless Metal Deposition on  
Integrated Circuit Bonds Pads.**  
Attorney Docket No. TI-30592  
Our File: 1000-2141

Dear Sir:

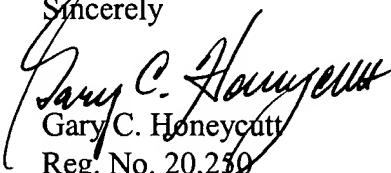
Enclosed for filing please find the following items relating to the above-identified application:

- (1) Non-Provisional Application/Fee Authorization/transmittal Form ;
- (2) Declaration, and Power of Attorney;
- (3) Recordation Form Cover Sheet with Assignment;
- (4) Specifications and Formal Drawings; and
- (5) Postcards.

Please charge **Deposit Account No. 20-0668** in the amount of the total fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to **Deposit Account No. 20-0668**.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely

  
Gary C. Honeycutt  
Reg. No. 20,250

GCH/ntn  
Enclosure

**Attorney Docket No. TI-30589**

Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the  
patent application of:

Inventor(s): **Gonzalo Amador**  
**Roger J. Stierman**

**"EXPRESS MAILING" Mailing Label No.**  
**EL690653937US.** Date of Deposit: **March 23, 2001.** I hereby certify that this paper is being deposited with the U.S. Postal Service Express Mail Post Office to Addressee Service under 37 CFR 1.10 on the date shown above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

~~Nancy Thornton~~

3/23/2001

## For: Fixture and Method for Uniform Electroless Metal Deposition on Integrated Circuit Bond Pads

Enclosed are:

2 Sheets of formal drawings and **18** pages of Specification (including Abstract)  
X A Declaration/Power of Attorney  
X Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 based upon **Provisional Patent Application number 60/193,615, filed 03/31/2000**.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 710.00
Total Claims	11	-20 =	0	X \$22 =	\$0.00
Independent Claims	2	- 3 =	0	X \$82 =	\$0.00
Total Filing Fee					\$710.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. **This form is submitted in triplicate.**

All correspondence related to this application may be addressed to the undersigned at Navarro IP Law Group, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: March 23, 2001

Gary C. Honeycutt  
Gary C. Honeycutt  
Registration No. 20,250